

Abstract**A structuring method**

5 The invention provides a structuring method, in particular
for stepped wafer or die surfaces. The method includes
photolithographically exposing a pattern comprising at
least a first pattern portion and a second pattern portion
10 onto a surface, said surface comprising at least a first
surface portion at which a tangential plane to the surface
extends in a first plane and a second surface portion at
which a tangential plane to the surface extends in a
second plane not coinciding with the first plane. The
method comprises a first exposure step, in which the first
15 pattern portion is exposed. Therein, the first pattern
portion is focused into a first focal plane. The method
further comprises a second exposure step, in which the
second pattern portion is exposed. Therein, the second
pattern portion is focused into a second focal plane which
20 is different from the first focal plane.

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